

**MORE LIGHT** 

# Wafer-Level PIC Testing Optical solution for high volume testing of photonic integrated circuits on wafer level Overview – 01/2020



## **Application and Market requirements**



**PIC-Wafer** 

Possible series configuration

## Application: **Opto-Electronical Probe Card Opto-Electronical Test Head Probe Card** for Wafer Level Test of Photonic Integrated Circuits (PICs) platform-based product Chuck **Optical Module** as **core component** enables: Wafer Prober Electrical and optical interfaces in a single probe card Fast and parallel qualification 'Plug & Play' with existing IC probers Easy and quick adaptation to different PIC designs

Functional model

## **Application and Market requirements**



#### What is the driver?



data center	
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### Increase Speed

of traffic inside data centers by...



#### Optical data transmission.

Switch from copper cables to **optical fibers.** 

#### **Signal conversion**

from electrical  $\rightarrow$  optical  $\rightarrow$  electrical inside the **Optical Transceivers** needed.



**PIC** - Photonic integrated circuit as core component.

#### **Connected World**

generates continuously growing

#### data traffic

with need for low latency.

## **Application and Market requirements**



The **PIC ecosystem** is still under development.

It needs to

- align with CMOS fabrication chain,
- meet current industry standards,
- reduce costs!

## → Opto-electronical testing plays a vital role!





### Current and Ideal Wafer Level Test Solutions

#### **Current solutions**

- are fiber based,

- Need active alignment in sub-micrometer range,
- separated probes (electrical and optical) and
- dedicated or customized probing equipment.
- Have **no** or only limited possibility for **parallelization**.

## **Ideal solution**

- would be Plug & Play' ready for existing standard IC wafer probers and automated test equipment,
- needs no active alignment time per chip,
- Parallel qualification → multi-DUT regime
- Can be operated by same personnel as standard IC equipment.





## **Technical Realization of a Demonstrator**





Measurement of a PIC as single-die

## **Probe Card Principle**







# Supporting the digital world.